



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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| Parameter | Ratings | Units |
|---------------------|---------|--------------------------------------|
| Blocking Voltage | 350 | V _P |
| Load Current | 120 | mA _{rms} / mA _{DC} |
| On-Resistance (max) | 35 | Ω |

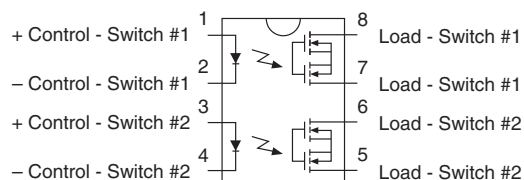
Features

- 3750V_{rms} Input/Output Isolation
- Current Limiting Device
- Low Drive Power Requirements (TTL/CMOS Compatible)
- No Moving Parts
- High Reliability
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Machine Insertable, Wave Solderable
- Surface Mount and Tape & Reel Versions Available
- Small 8-Pin Package

Applications

- Telecom Switching
 - Tip/Ring Circuits
 - Modem Switching (Laptop, Notebook, Pocket Size)
 - Hook Switch
 - Dial Pulsing
 - Ground Start
 - Ringing Injection
- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment-Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Pin Configuration



Description

LAA110L is a dual normally open (1-Form-A) Solid State Relay that has two independently controlled, optically coupled MOSFET switches with an additional current limiting circuit. The MOSFET switches and photovoltaic die use optically coupled MOSFET technology to provide 3750V_{rms} of input/output isolation.

The optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient GaAlAs infrared LED.

This dual switch OptoMOS relay provides a more compact design solution than discrete single-pole relays in a variety of applications, and saves board space by incorporating both switches in a single 8-Pin package.

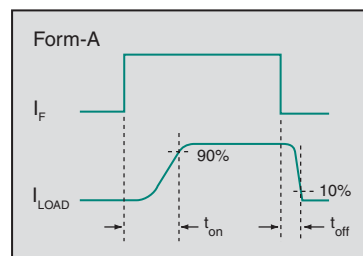
Approvals

- UL Recognized Component: File # E76270
- CSA Certified Component: Certificate # 1175739
- EN/IEC 60950-1 Certified Component:
TUV Certificate B 09 07 49410 004

Ordering Information

| Part # | Description |
|------------|----------------------------------|
| LAA110L | 8-Pin DIP (50/Tube) |
| LAA110LS | 8-Pin Surface Mount (50/Tube) |
| LAA110LSTR | 8-Pin Surface Mount (1,000/Reel) |
| LAA110PL | 8-Pin Flat Pack (50/Tube) |
| LAA110PLTR | 8-Pin Flat Pack (1,000/Reel) |

Switching Characteristics of Normally Open (Form A) Devices



Absolute Maximum Ratings @ 25°C

| Parameter | Ratings | Units |
|--------------------------------------|-------------|------------------|
| Blocking Voltage | 350 | V _P |
| Reverse Input Voltage | 5 | V |
| Input Control Current | 50 | mA |
| Peak (10ms) | 1 | A |
| Input Power Dissipation ¹ | 150 | mW |
| Total Power Dissipation ² | 800 | mW |
| Isolation Voltage, Input to Output | 3750 | V _{rms} |
| Operational Temperature | -40 to +85 | °C |
| Storage Temperature | -40 to +125 | °C |

¹ Derate linearly 1.33 mW / °C

² Derate linearly 6.67 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

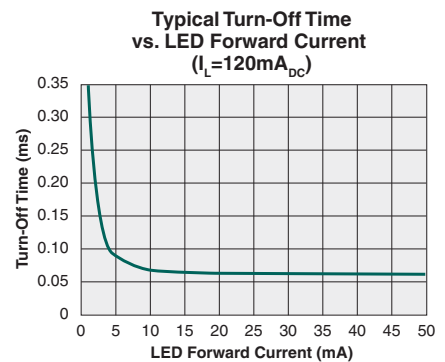
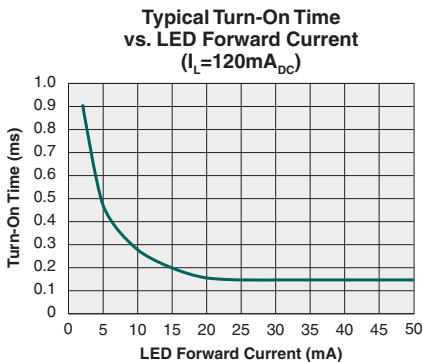
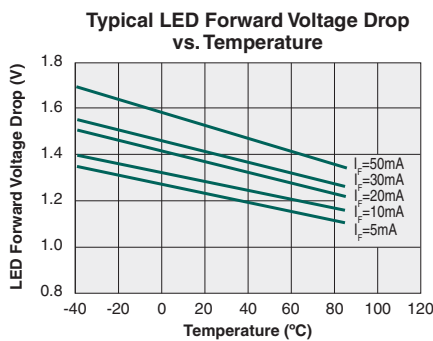
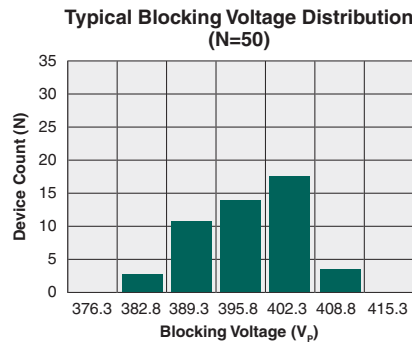
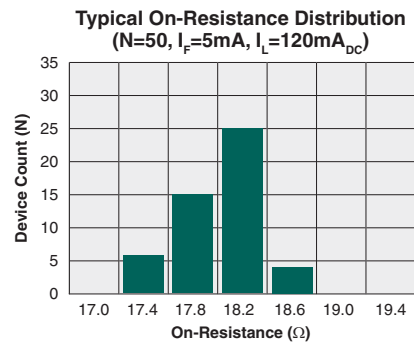
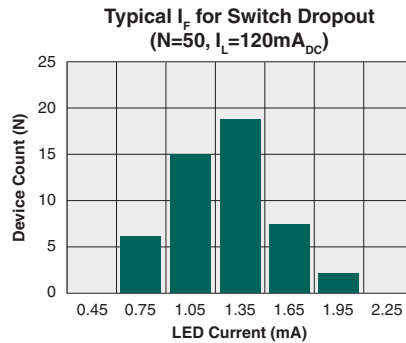
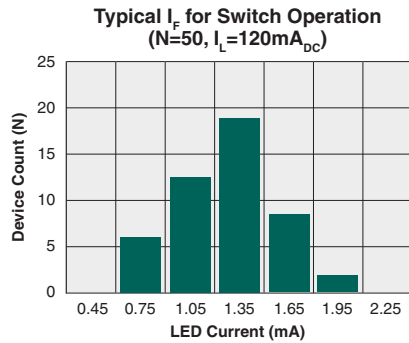
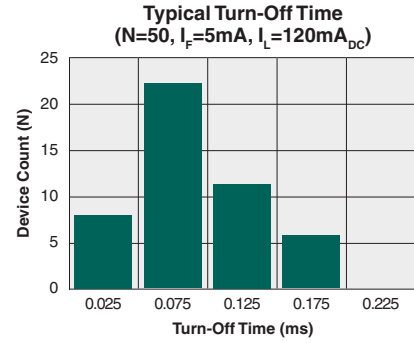
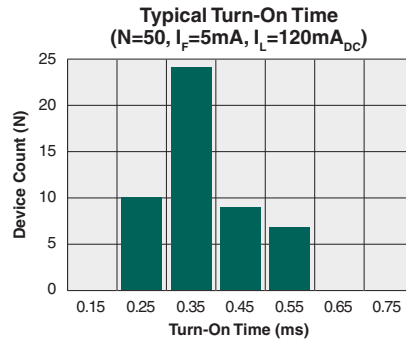
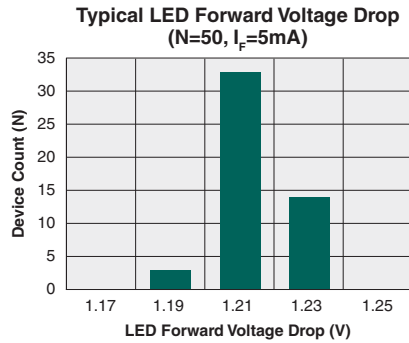
Electrical Characteristics @ 25°C

| Parameter | Conditions | Symbol | Min | Typ | Max | Units |
|---------------------------------------|--|-------------------|------|------|------|--------------------------------------|
| Output Characteristics | | | | | | |
| Load Current, Continuous ¹ | - | I _L | - | - | 120 | mA _{rms} / mA _{DC} |
| Load Current Limiting | V _L =8V, I _F =5mA | I _{CL} | ±130 | ±170 | ±210 | mA |
| On-Resistance ² | I _L =120mA | R _{ON} | - | 30 | 35 | Ω |
| Off-State Leakage Current | V _L =350V _P | I _{LEAK} | - | - | 1 | μA |
| Switching Speeds | I _F =5mA, V _L =10V | t _{on} | - | - | 3 | ms |
| Turn-On | | | | | | |
| Turn-Off | I _F =5mA, V _L =10V | t _{off} | - | - | 3 | ms |
| Output Capacitance | V _L =50V, f=1MHz | C _{OUT} | - | 25 | - | pF |
| Input Characteristics | | | | | | |
| Input Control Current to Activate | I _L =120mA | I _F | - | - | 5 | mA |
| Input Control Current to Deactivate | - | - | 0.4 | 0.7 | - | mA |
| Input Voltage Drop | I _F =5mA | V _F | 0.9 | 1.2 | 1.4 | V |
| Reverse Input Current | V _R =5V | I _R | - | - | 10 | μA |
| Common Characteristics | | | | | | |
| Input to Output Capacitance | - | C _{IO} | - | 3 | - | pF |

¹ If both poles operate, then the load current must be derated so that it does not exceed the package power dissipation value.

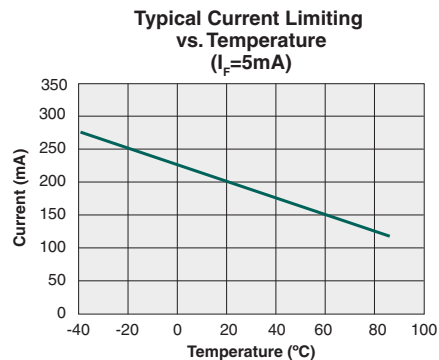
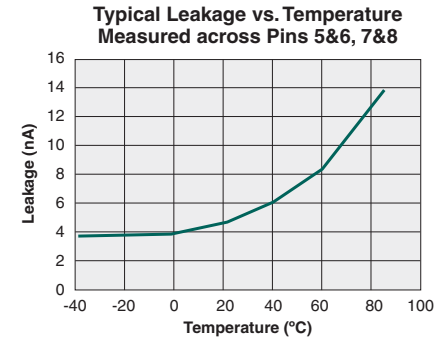
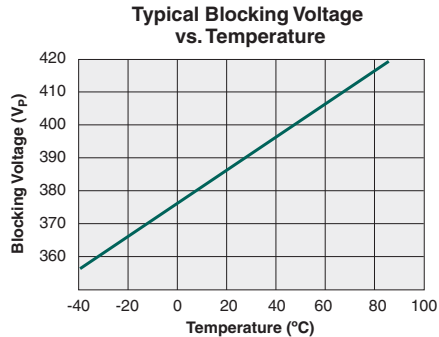
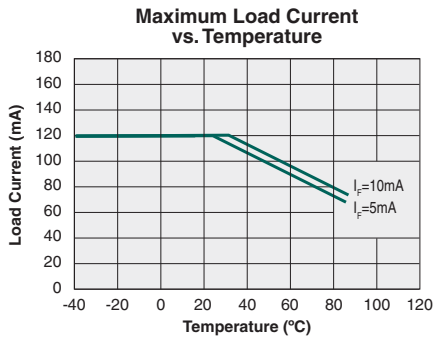
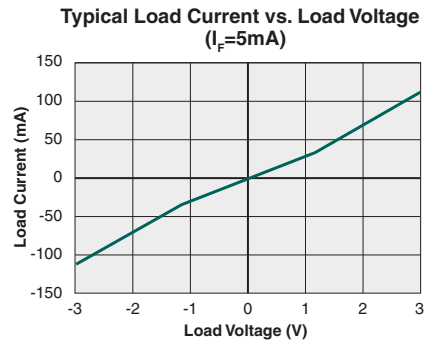
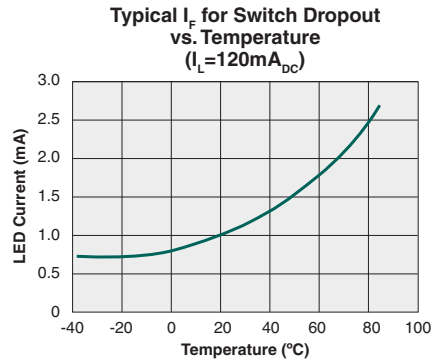
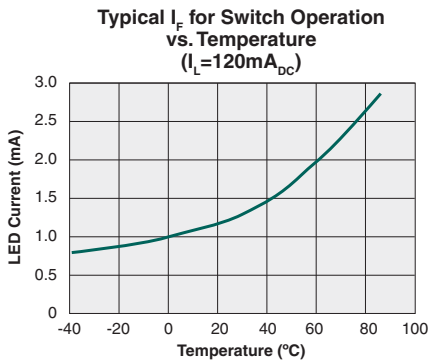
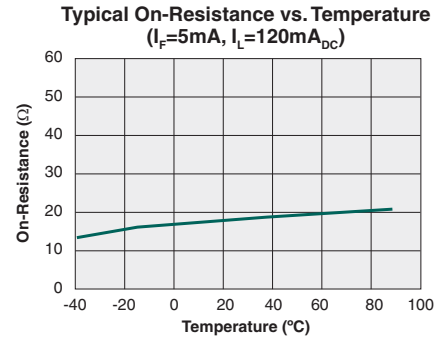
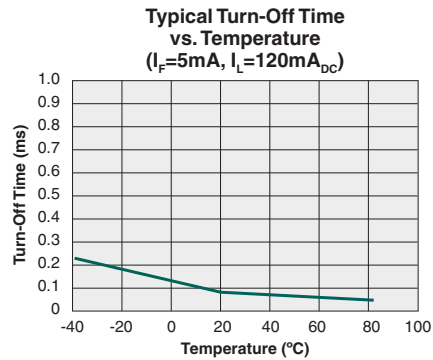
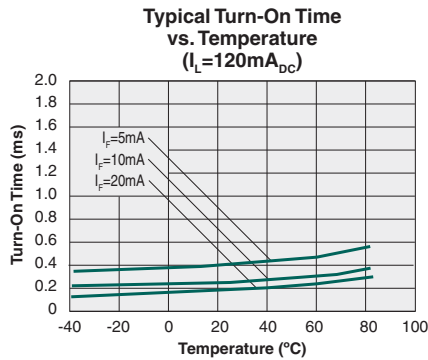
² Measurement taken within one second of on-time.

PERFORMANCE DATA @25°C (Unless Otherwise Noted)*



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

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Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

| Device | Moisture Sensitivity Level (MSL) Rating |
|-------------------------------|---|
| LAA110L / LAA110LS / LAA110PL | MSL 1 |

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

| Device | Maximum Temperature x Time |
|--------------------|----------------------------|
| LAA110L / LAA110LS | 250°C for 30 seconds |
| LAA110PL | 260°C for 30 seconds |

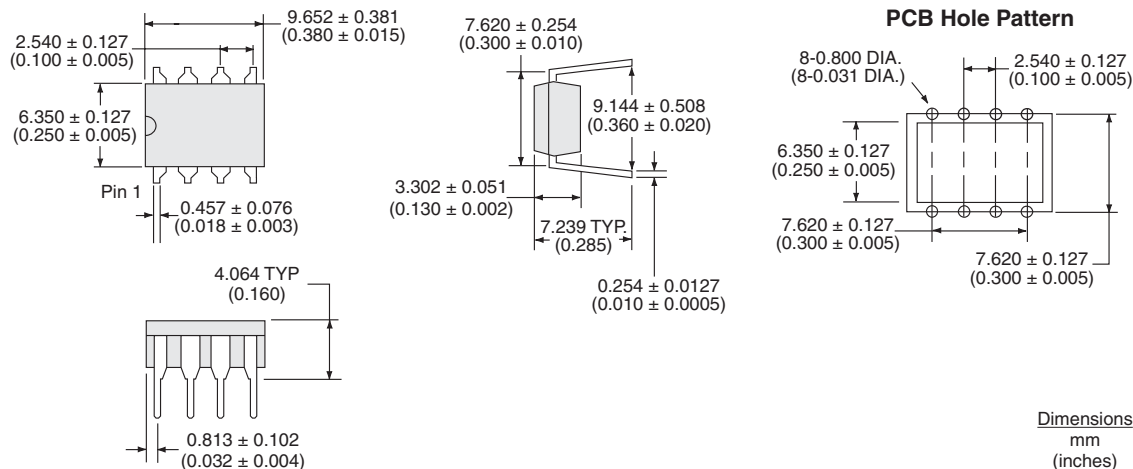
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

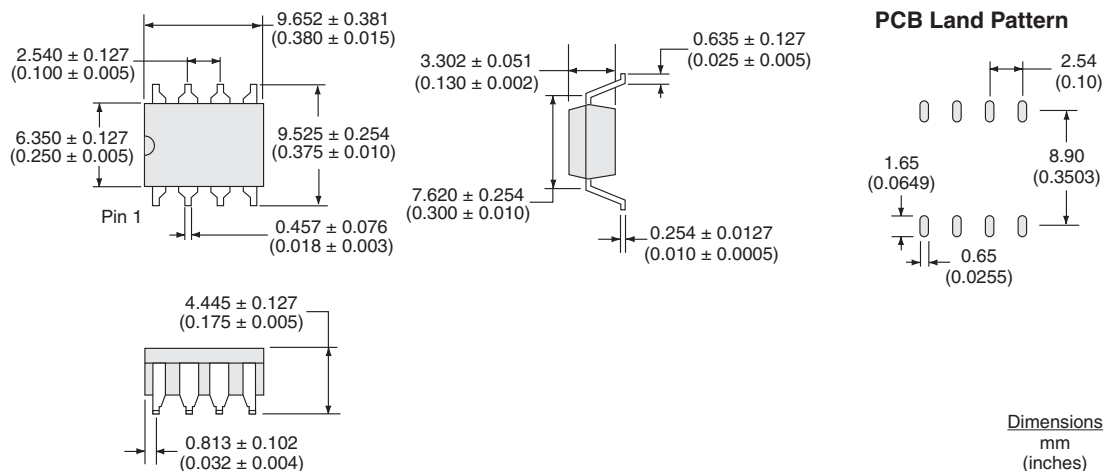


MECHANICAL DIMENSIONS

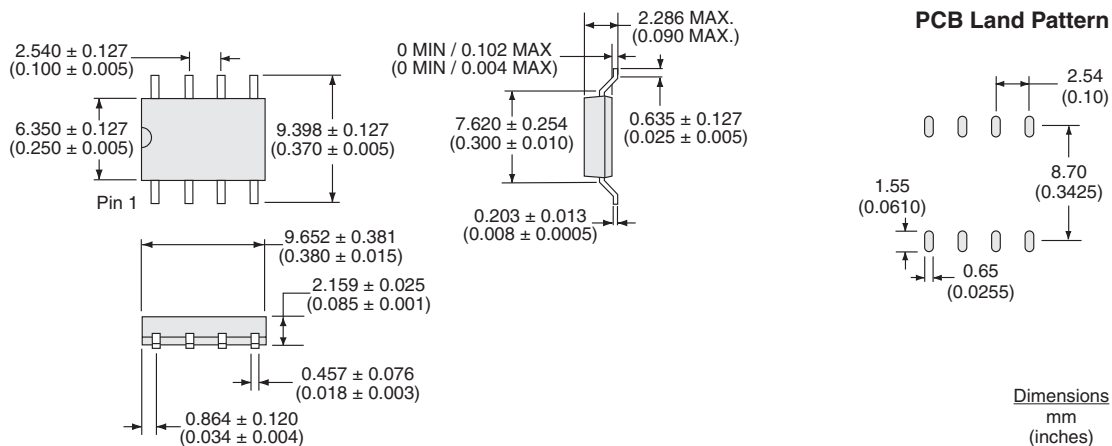
LAA110L



LAA110LS

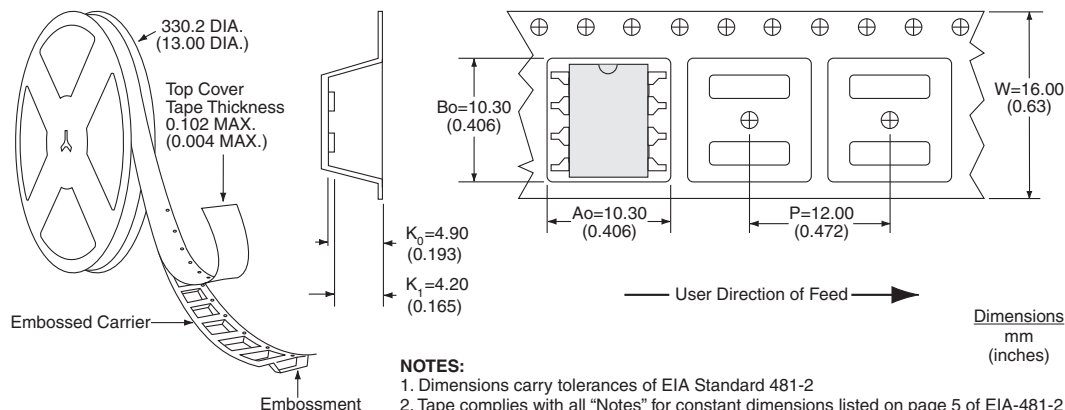


LAA110PL

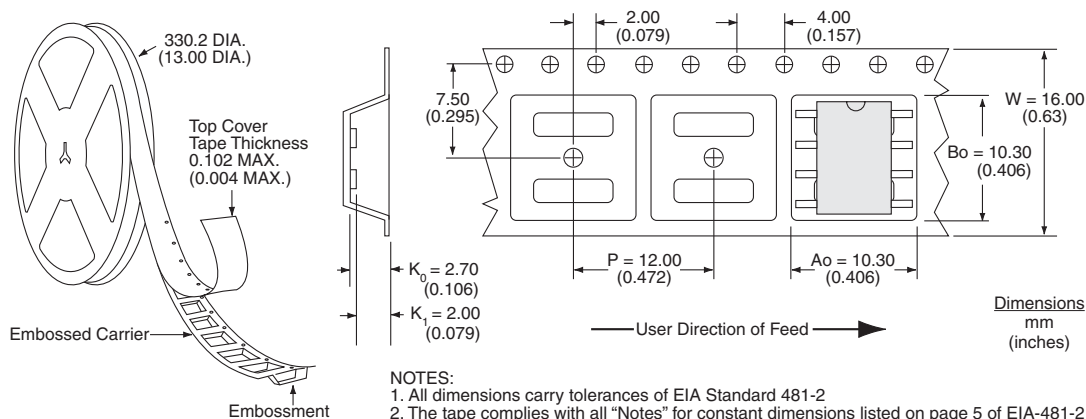


MECHANICAL DIMENSIONS

LAA110LSTR Tape & Reel



LAA110PLTR Tape & Reel



For additional information please visit our website at: www.ixysic.com

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